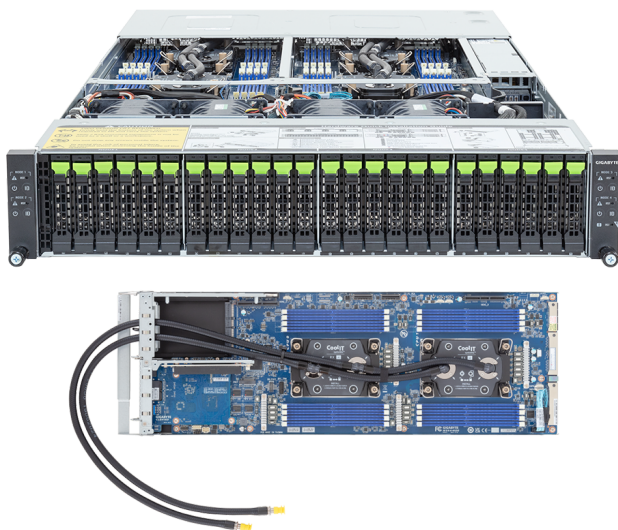


H274-S60-LAW1

High Density Server - Intel® Xeon® 6 -
2U 4-Node DP 24-Bay Gen5 NVMe/SATA/SAS-4 DLC



Key Features

- Direct liquid cooling solution
- 2U 4-node rear access server system
- Dual Intel® Xeon® 6700/6500-Series Processors per node
- 8-Channel DDR5 RDIMM / MRDIMM, 16 x DIMMs per node
- 8 x 1Gb/s LAN ports via Intel® I350-AM2
- 24 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 4 x M.2 slots with PCIe Gen4 x4 interface **(optional)**
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Applications

High-Performance Computing Server, High Converged Server,
Servers for Hybrid/Private Cloud...

Specification

Dimensions	2U 4-Node - Rear access (W440 x H87.5 x D877 mm)	PCIe Expansion Slots	4 x LP x16 PCIe Gen5 x16 4 x OCP NIC 3.0 PCIe Gen5 x16, Support NCSI
Motherboard	MS64-HD0	I/O Ports	Front: 1 x CMC status LED, 1 x CMC reset button Rear: 8 x USB 3.2 Gen1, 4 x Mini-DP, 8 x RJ45, 4 x MLAN
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors Dual processor per node, TDP up to 300W at 35°C ambient - No OCP cards at 35°C ambient, TDP up to 350W - With OCP cards at 30°C ambient, TDP up to 350W	Backplane Board	PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
OS Compatibility	OS Support List	TPM	4 x TPM headers (SPI), Optional TPM2.0 kit: CTM012 4 x PRoT connectors (only enabled on RoT SKU)
Socket	8 x LGA 4710 (Socket E2)	Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
Chipset	System on Chip	System Fans	4 x 80x80x80mm
Memory	8-Channel DDR5 RDIMM/MRDIMM, 64 x DIMMs [RDIMM] Up to 6400 MT/s [MRDIMM] Up to 8000 MT/s ^[1] ^[1] MRDIMMs are supported only on select Intel® Xeon® 6 processors with P-cores.	Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing) *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
LAN	8 x 1Gb/s LAN (4 x Intel® I350-AM2), Support NCSI 4 x 10/100/1000 Mbps Management LAN	Packaging Content	1 x H274-S60-LAW1 8 x CoolIT CPU cold plate loops 1 x Mini-DP to D-Sub cable 16 x Carriers 1 x 3-Section Rail kit
Video	Integrated in ASPEED® AST2600 x 4 - 4 x Mini-DP	Ordering Part Numbers	6NH274S60DR000LAW1*
Storage	Front hot-swap: 24 x 2.5" Gen5 NVMe/SATA/SAS-4 ^[1] Optional internal M.2: 4 x M.2 (2260/2280/22110), PCIe Gen4 x4 ^[1] SAS card is required to support SAS drives.	Optional Parts	- M.2 riser card - CMTP160: 9CMTP160NR-00* - CoolIT leak sensor board: 6NH274S60S1000LAW10 (QPA:4)
RAID	Require RAID add-in cards Onboard VROC key headers		



Learn more at: <https://www.gigabyte.com/Enterprise>

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